

Title (en)
INSULATING ADHESIVE COMPOSITION FOR METAL-BASED COPPER CLAD LAMINATE (MCCL), COATED METAL PLATE USING SAME, AND METHOD FOR MANUFACTURING SAME

Title (de)
ISOLIERENDE KLEBSTOFFZUSAMMENSETZUNG FÜR KUPFERKASCHIERTES LAMINAT AUF METALLBASIS, BESCHICHTETE METALLPLATTE DAMIT UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
COMPOSITION ADHÉSIVE ISOLANTE POUR UN STRATIFIÉ PLAQUÉ CUIVRE À BASE MÉTALLIQUE (MCCL), PLAQUE MÉTALLIQUE REVÊTUE L'UTILISANT ET SON PROCÉDÉ DE FABRICATION

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Application
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Abstract (en)
[origin: EP2799509A1] The present invention relates to an insulating adhesive composition for metal printed circuit board, an adhesive-coated metal plate using the same, and a method for manufacturing the adhesive-coated metal plate. The adhesive composition according to the present invention forms an adhesive layer that is excellent in terms of adhesion to a copper foil, electrical insulating properties, and thermal resistance. The composition contains a specific epoxy resin, a curing agent and alumina. According to the present invention, in coating the metal plate with the solvent type adhesive, a roll coating method is used to perform a continuous coating process on the metal plate, thereby improving productivity when compared to the general method using a sheet type adhesive film.

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Citation (search report)
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